# imall

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## Low-Voltage CMOS Quad **2-Input NOR Gate**

### With 5 V-Tolerant Inputs

The MC74LCX02 is a high performance, quad 2-input NOR gate operating from a 2.3 to 3.6 V supply. High impedance TTL compatible inputs significantly reduce current loading to input drivers while TTL compatible outputs offer improved switching noise performance. A VI specification of 5.5 V allows MC74LCX02 inputs to be safely driven from 5 V devices.

Current drive capability is 24 mA at the outputs.

#### Features

- Designed for 2.3 V to 3.6 V V<sub>CC</sub> Operation
- 5 V Tolerant Inputs Interface Capability With 5 V TTL Logic
- LVTTL Compatible
- LVCMOS Compatible
- 24 mA Balanced Output Sink and Source Capability
- Near Zero Static Supply Current (10 µA) Substantially Reduces System Power Requirements
- Latchup Performance Exceeds 500 mA
- ESD Performance: Human Body Model >2000 V; Machine Model >200 V
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

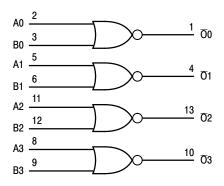


Figure 1. Logic Diagram

#### **PIN NAMES**

Pins	Function
An, Bn	Data Inputs
Ōn	Outputs



#### **ON Semiconductor®**

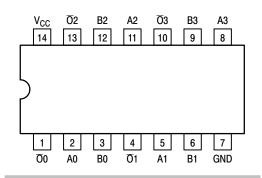
http://onsemi.com



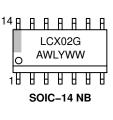
D SUFFIX CASE 751A

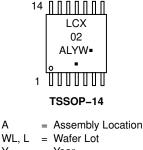
TSSOP-14 DT SUFFIX **CASE 948G** 





#### MARKING DIAGRAMS





= Year WW, W = Work Week G or = Pb-Free Package

Α

(Note: Microdot may be in either location)

#### **ORDERING INFORMATION**

See detailed ordering and shipping information in the package dimensions section on page 5 of this data sheet.

#### **TRUTH TABLE**

Inputs		Outputs
An	Bn	Ōn
L	L	Н
L	н	L
н	L	L
н	н	L

H = High Voltage Level L = Low Voltage Level

For I<sub>CC</sub> reasons, DO NOT FLOAT Inputs

#### **MAXIMUM RATINGS**

Symbol	Parameter	Value	Condition	Unit
V <sub>CC</sub>	DC Supply Voltage	-0.5 to +7.0		V
VI	DC Input Voltage	$-0.5 \leq V_I \leq +7.0$		V
Vo	DC Output Voltage	$-0.5 \leq V_O \leq V_{CC} + 0.5$	Output in HIGH or LOW State (Note 1)	V
I <sub>IK</sub>	DC Input Diode Current	-50	V <sub>I</sub> < GND	mA
I <sub>OK</sub>	DC Output Diode Current	-50	V <sub>O</sub> < GND	mA
		+50	$V_{\rm O} > V_{\rm CC}$	mA
Ι <sub>Ο</sub>	DC Output Source/Sink Current	±50		mA
I <sub>CC</sub>	DC Supply Current Per Supply Pin	±100		mA
I <sub>GND</sub>	DC Ground Current Per Ground Pin	±100		mA
T <sub>STG</sub>	Storage Temperature Range	-65 to +150		°C
MSL	Moisture Sensitivity		Level 1	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected. 1. I<sub>O</sub> absolute maximum rating must be observed.

#### **RECOMMENDED OPERATING CONDITIONS**

Symbol	Parameter		Min	Туре	Мах	Unit
V <sub>CC</sub>	11,5 8	erating a Retention Only	2.0 1.5	2.5, 3.3 2.5, 3.3	3.6 3.6	V
VI	Input Voltage		0		5.5	V
V <sub>O</sub>		GH or LOW State) State)	0		V <sub>CC</sub>	V
I <sub>OH</sub>	Vcc	$ \begin{array}{l} c = 3.0 \ \text{V} - 3.6 \ \text{V} \\ c = 2.7 \ \text{V} - 3.0 \ \text{V} \\ c = 2.3 \ \text{V} - 2.7 \ \text{V} \end{array} $			-24 -12 -8	mA
I <sub>OL</sub>	Vcc	$ \begin{array}{l} c = 3.0 \ \text{V} - 3.6 \ \text{V} \\ c = 2.7 \ \text{V} - 3.0 \ \text{V} \\ c = 2.3 \ \text{V} - 2.7 \ \text{V} \end{array} $			+24 +12 +8	mA
T <sub>A</sub>	Operating Free-Air Temperature		-40		+85	°C
$\Delta t / \Delta V$	Input Transition Rise or Fall Rate, V <sub>IN</sub> from 0.8 V t	o 2.0 V, V <sub>CC</sub> = 3.0 V	0		10	ns/V

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

#### DC ELECTRICAL CHARACTERISTICS

			T <sub>A</sub> = −40°C	to +85°C	
Symbol	Characteristic	Condition	Min	Max	Unit
V <sub>IH</sub>	HIGH Level Input Voltage (Note 2)	$2.3~V \leq V_{CC} \leq 2.7~V$	1.7		V
	$2.7 \text{ V} \le \text{V}_{\text{CC}} \le 3.6 \text{ V}$		2.0		
V <sub>IL</sub>	LOW Level Input Voltage (Note 2)	$2.3~V \leq V_{CC} \leq 2.7~V$		0.7	V
		$2.7~V \leq V_{CC} \leq 3.6~V$		0.8	
V <sub>OH</sub>	HIGH Level Output Voltage	$2.3~V \leq V_{CC} \leq 3.6~V;~I_{OH} = -100~\mu A$	V <sub>CC</sub> – 0.2		V
		$V_{CC} = 2.3 \text{ V}; \text{ I}_{OH} = -8 \text{ mA}$	1.8		
		$V_{CC} = 2.7 \text{ V}; I_{OH} = -12 \text{ mA}$	2.2		
		$V_{CC} = 3.0 \text{ V}; \text{ I}_{OH} = -18 \text{ mA}$	2.4		
		$V_{CC} = 3.0 \text{ V}; \text{ I}_{OH} = -24 \text{ mA}$	2.2		
V <sub>OL</sub>	LOW Level Output Voltage	2.3 V $\leq$ V_{CC} $\leq$ 3.6 V; I_{OL} = 100 $\mu A$		0.2	V
		$V_{CC} = 2.3 \text{ V}; \text{ I}_{OL} = 8 \text{ mA}$		0.6	
		$V_{CC} = 2.7 \text{ V}; \text{ I}_{OL} = 12 \text{ mA}$		0.4	
		V <sub>CC</sub> = 3.0 V; I <sub>OL</sub> = 16 mA		0.4	
		$V_{CC} = 3.0 \text{ V}; \text{ I}_{OL} = 24 \text{ mA}$		0.55	
I <sub>OFF</sub>	Power Off Leakage Current	$V_{CC}$ = 0, $V_{IN}$ = 5.5 V or $V_{OUT}$ = 5.5 V		10	μA
I <sub>IN</sub>	Input Leakage Current	$V_{CC}$ = 3.6 V, $V_{IN}$ = 5.5 V or GND		±5	μA
I <sub>CC</sub>	Quiescent Supply Current	$V_{CC}$ = 3.6 V, $V_{IN}$ = 5.5 V or GND		10	μA
$\Delta I_{CC}$	Increase in I <sub>CC</sub> per Input	$2.3 \leq V_{CC} \leq 3.6 \text{ V}; \text{ V}_{IH} = V_{CC} - 0.6 \text{ V}$		500	μΑ

2. These values of  $V_I$  are used to test DC electrical characteristics only.

#### AC CHARACTERISTICS (t\_R = t\_F = 2.5 ns; R\_L = 500 $\Omega$ )

				Limits					
				T <sub>A</sub> = −40°C to +85°C					
			V <sub>CC</sub> = 3.3	$V_{CC} = 3.3 V \pm 0.3 V$ $V_{CC} = 2.7 V$ $V_{CC} = 2.5 V \pm 0.2 V$					
			C <sub>L</sub> = 50 pF C		C <sub>L</sub> = 5	50 pF	C <sub>L</sub> =	30 pF	
Symbol	Parameter	Waveform	Min	Max	Min	Max	Min	Max	Unit
t <sub>PLH</sub>	Propagation Delay Time	1	1.5	5.5	1.5	6.2	1.5	6.6	ns
t <sub>PHL</sub>	Input-to-Output		1.5	5.5	1.5	6.2	1.5	6.6	
t <sub>OSHL</sub>	Output-to-Output Skew			1.0					ns
t <sub>OSLH</sub>	(Note 3)			1.0					

 Skew is defined as the absolute value of the difference between the actual propagation delay for any two separate outputs of the same device. The specification applies to any outputs switching in the same direction, either HIGH-to-LOW (t<sub>OSHL</sub>) or LOW-to-HIGH (t<sub>OSLH</sub>); parameter guaranteed by design.

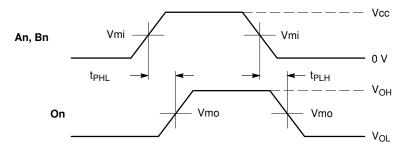
#### DYNAMIC SWITCHING CHARACTERISTICS

			T <sub>A</sub> = +25°C			
Symbol	Characteristic	Condition	Min	Тур	Max	Unit
V <sub>OLP</sub>	Dynamic LOW Peak Voltage	$V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $V_{IH}$ = 3.3 V, $V_{IL}$ = 0 V		0.8		V
	(Note 4)	$V_{CC}$ = 2.5 V, $C_L$ = 30 pF, $V_{IH}$ = 2.5 V, $V_{IL}$ = 0 V		0.6		V
V <sub>OLV</sub>	Dynamic LOW Valley Voltage	$V_{CC}$ = 3.3 V, $C_L$ = 50 pF, $V_{IH}$ = 3.3 V, $V_{IL}$ = 0 V		-0.8		V
	(Note 4)	$V_{CC}$ = 2.5 V, $C_L$ = 30 pF, $V_{IH}$ = 2.5 V, $V_{IL}$ = 0 V		-0.6		V

4. Number of outputs defined as "n". Measured with "n-1" outputs switching from HIGH-to-LOW or LOW-to-HIGH. The remaining output is measured in the LOW state.

#### **CAPACITIVE CHARACTERISTICS**

Symbol	Parameter	Condition	Typical	Unit
C <sub>IN</sub>	Input Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	7	pF
C <sub>OUT</sub>	Output Capacitance	$V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	8	pF
C <sub>PD</sub>	Power Dissipation Capacitance	10 MHz, $V_{CC}$ = 3.3 V, $V_{I}$ = 0 V or $V_{CC}$	25	pF

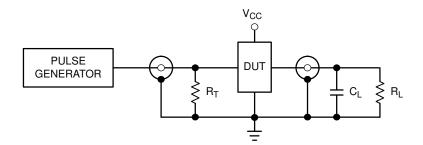


WAVEFORM 1 - PROPAGATION DELAYS

 $t_R$  =  $t_F$  = 2.5 ns, 10% to 90%; f = 1 MHz;  $t_W$  = 500 ns

	Vcc				
Symbol	3.3 V <u>+</u> 0.3 V	2.7 V	2.5 V <u>+</u> 0.2 V		
Vmi	1.5 V	1.5 V	Vcc/2		
Vmo	1.5 V	1.5 V	Vcc/2		

Figure 2. AC Waveforms



 $C_L = 50 \text{ pF}$  at  $V_{CC} = 3.3 \pm 0.3 \text{ V}$  or equivalent (includes jig and probe capacitance)  $C_L = 30 \text{ pF}$  at  $V_{CC} = 2.5 \pm 0.2 \text{ V}$  or equivalent (includes jig and probe capacitance)  $R_L = R_1 = 500 \Omega$  or equivalent

 $R_T = Z_{OUT}$  of pulse generator (typically 50  $\Omega$ )

Figure 3. Test Circuit

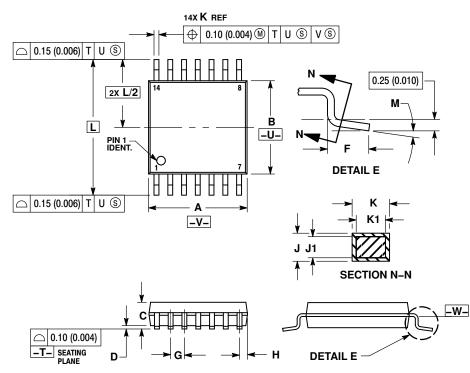
#### **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC74LCX02DG	SOIC-14 NB (Pb-Free)	55 Units / Rail
MC74LCX02DR2G	SOIC-14 NB (Pb-Free)	2500 Tape & Reel
MC74LCX02DTG	TSSOP-14 (Pb-Free)	96 Units / Rail
MC74LCX02DTR2G	TSSOP-14 (Pb-Free)	2500 Tape & Reel

+For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

#### PACKAGE DIMENSIONS

TSSOP-14 DT SUFFIX CASE 948G **ISSUE B** 



NOTES:

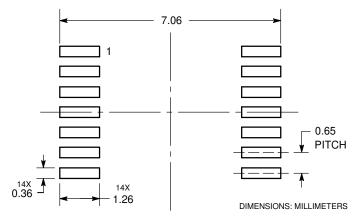
DTES:
DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: MILLIMETER.
DIMENSION A DOES NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS. MOLD FLASH OR GATE BURRS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
DIMENSION B DOES NOT INCLUDE INTERLEAD FLASH OR PROTRUSION. INTERLEAD FLASH OR PROTRUSION. S. DIMENSION K DOES NOT INCLUDE

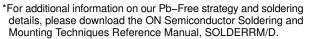
5. DIMENSION K DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE K DIMENSION AT MAXIMUM MATERIAL

CONDITION. 6. TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY. 7. DIMENSION A AND B ARE TO BE DETERMINED AT DATUM PLANE -W-.

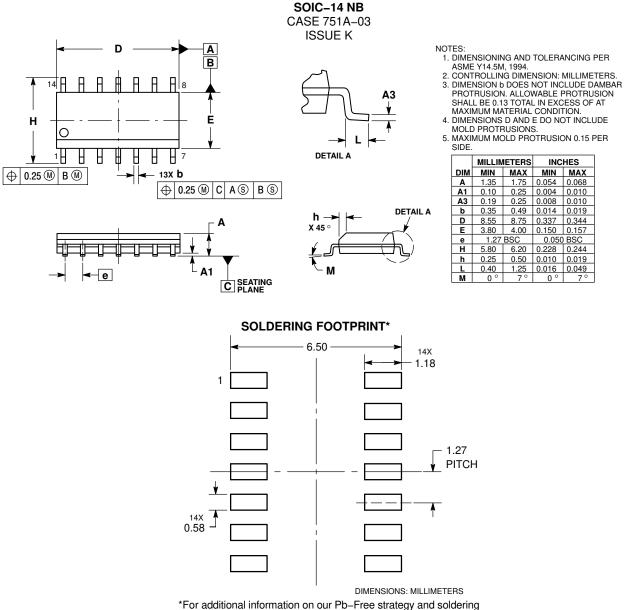
	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	4.90	5.10	0.193	0.200
В	4.30	4.50	0.169	0.177
С		1.20		0.047
D	0.05	0.15	0.002	0.006
F	0.50	0.75	0.020	0.030
G	0.65	BSC	0.026	BSC
Н	0.50	0.60	0.020	0.024
J	0.09	0.20	0.004	0.008
J1	0.09	0.16	0.004	0.006
Κ	0.19	0.30	0.007	0.012
K1	0.19	0.25	0.007	0.010
L	6.40	6.40 BSC		BSC
М	0 °	8 °	0 °	8 °

SOLDERING FOOTPRINT\*





#### PACKAGE DIMENSIONS



\*For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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